

# P-Channel 20-V (D-S) MOSFET

MOSFET	PRODUCT SUMM	ARY	
V <sub>DS</sub> (V)	$R_{DS(on)}(\Omega)$	I <sub>D</sub> (A) <sup>a</sup>	Q <sub>g</sub> (Typ.)
	0.035 at V <sub>GS</sub> = - 10 V	- 5 <sup>e</sup>	
- 20	0.043 at V <sub>GS</sub> = - 4.5 V	- 5 <sup>e</sup>	10 nC
	0.061 at V <sub>GS</sub> = - 2.5 V	- 4.8	

## **APPLICATIONS** Load Switch



HALOGEN **FREE** 

- PA Switch

**FEATURES** 

**Definition** 

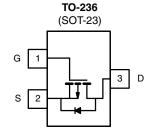
100 % R<sub>g</sub> Tested

Halogen-free According to IEC 61249-2-21

Compliant to RoHS Directive 2002/95/EC

TrenchFET® Power MOSFET

DC/DC Converters



ABSOLUTE MAXIMUM RATINGS (TA	= 25 °C, unless ot	herwise noted)		
Parameter		Symbol	Limit	Unit
Drain-Source Voltage		V <sub>DS</sub>	- 20	V
Gate-Source Voltage		$V_{GS}$	± 12	V
	T <sub>C</sub> = 25 °C		- 5 <sup>e</sup>	
Continuous Drain Current (T <sub>.1</sub> = 150 °C)	T <sub>C</sub> = 70 °C	I <sub>D</sub>	- 4.8	
Continuous Diam Current (1) = 130 °C)	T <sub>A</sub> = 25 °C	טי	- 4.5 <sup>b, c</sup>	
	T <sub>A</sub> = 70 °C		- 3.5 <sup>b, c</sup>	Α
Pulsed Drain Current		I <sub>DM</sub>	- 18	
Continuous Source-Drain Diode Current	T <sub>C</sub> = 25 °C	l <sub>o</sub>	- 2.1	
Continuous Source-Diam Diode Current	T <sub>A</sub> = 25 °C	Is	- 1.0 <sup>b, c</sup>	
	T <sub>C</sub> = 25 °C		2.5	
Maximum Bowar Dissination	T <sub>C</sub> = 70 °C	P <sub>D</sub>	1.6	□ w
Maximum Power Dissipation	T <sub>A</sub> = 25 °C	' D	1.25 <sup>b, c</sup>	VV
	T <sub>A</sub> = 70 °C		0.8 <sup>b, c</sup>	
Operating Junction and Storage Temperature Range		T <sub>J</sub> , T <sub>stq</sub>	- 55 to 150	°C

THERMAL RESISTANCE RATINGS							
Parameter		Symbol	Typical	Maximum	Unit		
Maximum Junction-to-Ambient <sup>b, d</sup>	≤5 s	R <sub>thJA</sub>	75	100	°C/W		
Maximum Junction-to-Foot (Drain)	Steady State	$R_{thJF}$	40	50	]		

#### Notes:

- a. Based on  $T_C$  = 25 °C. b. Surface mounted on 1" x 1" FR4 board.
- d. Maximum under steady state conditions is 166 °C/W.
- e. Package limited.



Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit
Static	·			<u>'I</u>		
Drain-Source Breakdown Voltage	$V_{DS}$	$V_{DS} = 0 \text{ V}, I_D = -250 \mu\text{A}$	- 20			V
V <sub>DS</sub> Temperature Coefficient	$\Delta V_{DS}/T_{J}$	J 050 A		- 13.4		mV/°C
V <sub>GS(th)</sub> Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	I <sub>D</sub> = - 250 μΑ		2.9		lillv/ C
Gate-Source Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_{D} = -250 \mu\text{A}$	- 0.5		- 1.5	V
Gate-Source Leakage	I <sub>GSS</sub>	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 12 \text{ V}$			± 100	nA
	I <sub>DSS</sub>	V <sub>DS</sub> = - 20 V, V <sub>GS</sub> = 0 V			- 1	μΑ
Zero Gate Voltage Drain Current		$V_{DS} = -20 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 55 ^{\circ}\text{C}$			- 10	
On-State Drain Current <sup>a</sup>	I <sub>D(on)</sub>	$V_{DS} \le -5 \text{ V}, V_{GS} = -4.5 \text{ V}$	- 18			Α
		V <sub>GS</sub> = - 10 V, I <sub>D</sub> = - 5.1 A		0.035		
Drain-Source On-State Resistance <sup>a</sup>	R <sub>DS(on)</sub>	V <sub>GS</sub> = - 4.5 V, I <sub>D</sub> = - 4.5 A		0.043		nA μA
	, ,	V <sub>GS</sub> = - 2.5 V, I <sub>D</sub> = - 3.7 A		0.061		
Forward Transconductance <sup>a</sup>	9 <sub>fs</sub>	V <sub>DS</sub> = - 5 V, I <sub>D</sub> = - 5.1 A		15		S
Dynamic <sup>b</sup>	l			"		<u>'</u>
Input Capacitance	C <sub>iss</sub>			835		
Output Capacitance	C <sub>oss</sub>			180		pF
Reverse Transfer Capacitance	C <sub>rss</sub>			155		
Tatal Oata Ohanna		V <sub>DS</sub> = - 10 V, V <sub>GS</sub> = - 4.5 V, I <sub>D</sub> = - 5.1 A		10	10	
Total Gate Charge	$Q_g$			6.4		1
Gate-Source Charge	Q <sub>gs</sub>	V <sub>DS</sub> = - 10 V, V <sub>GS</sub> = - 2.5 V, I <sub>D</sub> = - 5.1 A		1.7		nC
Gate-Drain Charge	$Q_{gd}$			3.4		1
Gate Resistance	$R_g$	f = 1 MHz	0.9	4.4	8.8	Ω
Turn-On Delay Time	t <sub>d(on)</sub>			22	33	
Rise Time	t <sub>r</sub>	$V_{DD} = -10 \text{ V, R}_{L} = 2.4 \Omega$		20	30	ns
Turn-Off Delay Time	t <sub>d(off)</sub>	$I_D = -4.1 \text{ A}, V_{GEN} = -4.5 \text{ V}, R_g = 1 \Omega$		28	42	
Fall Time	t <sub>f</sub>			9	18	
<b>Drain-Source Body Diode Characteristi</b>	cs			I		
Continuous Source-Drain Diode Current	I <sub>S</sub>	T <sub>C</sub> = 25 °C			- 2.1	
Pulse Diode Forward Current <sup>a</sup>	I <sub>SM</sub>				- 20	A
Body Diode Voltage	V <sub>SD</sub>	I <sub>S</sub> = - 4.1 A		- 0.8	- 1.2	V
Body Diode Reverse Recovery Time	t <sub>rr</sub>			23	35	ns
Body Diode Reverse Recovery Charge	Q <sub>rr</sub>	1 4 4 4 4 4 4 4 4 4 4 4 4 4 4 4 4 4 4 4		12	20	nC
Reverse Recovery Fall Time	t <sub>a</sub>	$I_F = -4.1 \text{ A, dI/dt} = 100 \text{ A/}\mu\text{s, T}_J = 25 ^{\circ}\text{C}$		15		1
Reverse Recovery Rise Time				8		ns

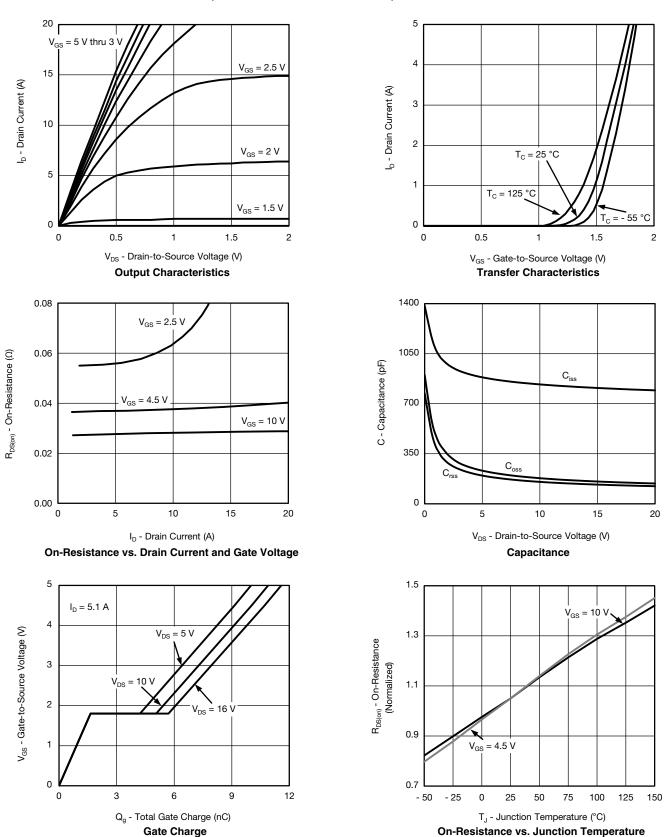
#### Notes:

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

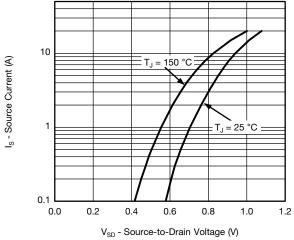
a. Pulse test; pulse width  $\leq$  300  $\mu s,$  duty cycle  $\leq$  2 %.

b. Guaranteed by design, not subject to production testing.

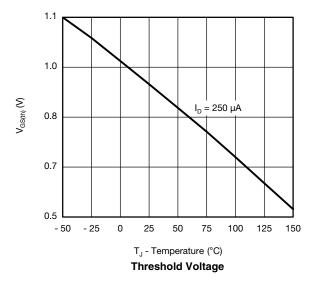


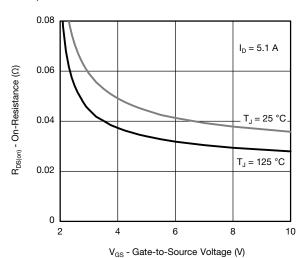




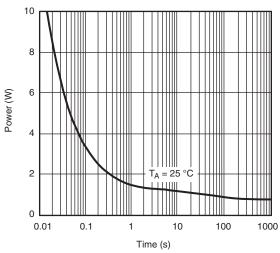


#### Source-Drain Diode Forward Voltage

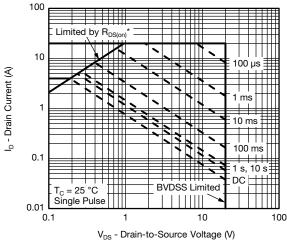




On-Resistance vs. Gate-to-Source Voltage



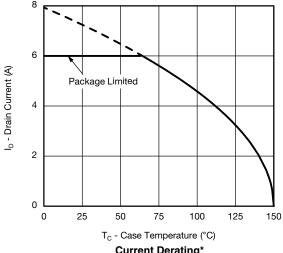
Single Pulse Power



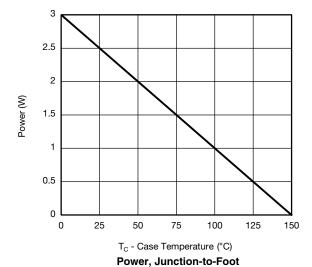
 $v_{DS}$  - Drain-to-Source voltage (v) \*  $V_{GS}$  > minimum  $V_{GS}$  at which  $R_{DS(on)}$  is specified

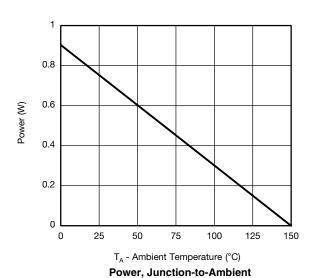
Safe Operating Area





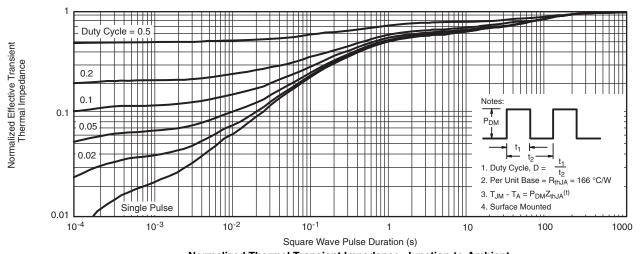
**Current Derating\*** 

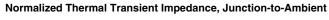


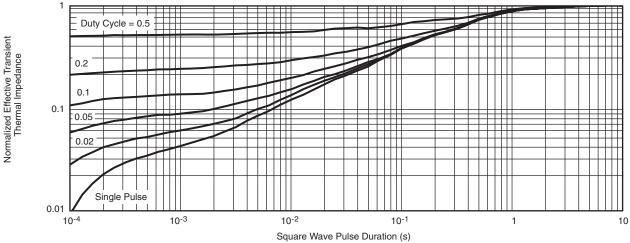


 $<sup>^*</sup>$  The power dissipation  $P_D$  is based on  $T_{J(max)}$  = 150  $^{\circ}$ C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.





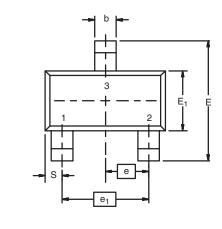


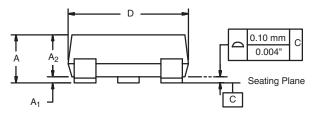


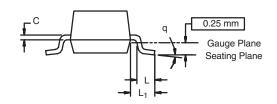
Normalized Thermal Transient Impedance, Junction-to-Foot



## SOT-23 (TO-236): 3-LEAD





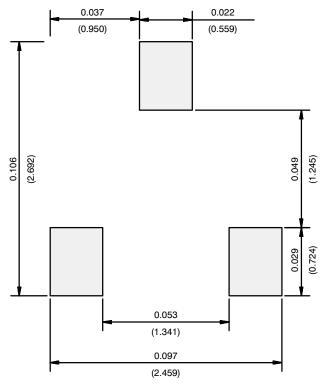


Dim	MILLIMETERS		INCHES	
	Min	Max	Min	Max
Α	0.89	1.12	0.035	0.044
A <sub>1</sub>	0.01	0.10	0.0004	0.004
A <sub>2</sub>	0.88	1.02	0.0346	0.040
b	0.35	0.50	0.014	0.020
С	0.085	0.18	0.003	0.007
D	2.80	3.04	0.110	0.120
E	2.10	2.64	0.083	0.104
E <sub>1</sub>	1.20	1.40	0.047	0.055
е	0.95 BSC		0.0374 Ref	
e <sub>1</sub>	1.90	1.90 BSC		8 Ref
L	0.40	0.60	0.016	0.024
L <sub>1</sub>	0.64 Ref		0.025	5 Ref
S	0.50 Ref		0.020 Ref	
q	3°	8°	3°	8°

DWG: 5479



#### **RECOMMENDED MINIMUM PADS FOR SOT-23**



Recommended Minimum Pads Dimensions in Inches/(mm)

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